laser annealing the amorphous semiconductor material to form a single crystalline semiconductor layer containing germanium; 6 doping the single crystalline semiconductor layer and the substrate at a source location and a drain location to form a source region and a drain region, whereby a channel region between the source region and the drain region includes a thin semiconductor germanium region; and 10 siliciding the source region and the drain region to form a silicide 11 layer, the silicide layer extending into the substrate. 12 (Thrice Amended) The method of claim 1, further comprising: 11. 1 providing a second amorphous semiconductor material above the 2 amorphous semiconductor material including germanium after the laser 3 4 annealing step; performing another laser annealing step to form a second single 5 crystalline semiconductive layer from the second amorphous semiconductor 6 material; and wherein the siliciding step forms the silicide layer so that the depth of the silicided layer is deeper than the second single crystalline 9 semiconductor layer. 10 (Twice Amended) A method of manufacturing an ultra-large scale 12. 11 integrated circuit including a transistor, the method comprising steps of: 12 depositing an amorphous silicon germanium material above a top surface of a semiconductor substrate; first annealing the amorphous silicon germanium material; 15 depositing an amorphous silicon material above the silicon 16 germanium material; 17 second annealing the amorphous silicon material; and 18 providing a source region and a drain region for the transistor, the 19 source region and the drain region being deeper than a combined thickness of 20

## Please add new Claim 29

the silicon germanium material and the silicon material.

29. (New)The method of claim 12 further comprising:

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siliciding the source and the drain region to form a silicide layer, wherein the silicide layer extends deeper than the combined thickness.